

20-3305

LOW VISCOSITY THERMAL SHOCK EPOXY

DESCRIPTION:

20-3305 is a two part epoxy system formulated to meet the most critical electronic encapsulating requirements. This system has low shrinkage with excellent electrical properties. The low viscosity makes it ideal for potting, sealing, encapsulating, and casting applications.

20-3305 is ideal for thermal shock exposure. It has excellent adhesion to most substrates and forms a hermetic like seal to protect encapsulated parts. Great choice for high voltage applications.

TYPICAL SPECIFICATIONS:

Mix ratio, by weight	100:25
Mixed viscosity @ 25°C, cps	5,000
Color	Tan or Black
Gel time, 30 gram mass @ 120°C	
Minutes	50
Specific gravity	
Resin	1.80
Hardener	1.03
Hardness, shore D @ 25°C	70
Tensile strength, psi	1,550
Tensile Modulus, Kpsi	39,155
Operating temperature, °C	-55 to +155
Moisture Absorption, 24 hrs, %	0.14
Dielectric strength, V/mil	1857
Dielectric constant,	
1 kHz	3.67
100 kHz	3.86
Dissipation factor,	
1 kHz	0.025
100 kHz	0.016
Volume resistivity, ohm-cm	2.62×10^{16}
Surface Resistivity, ohms	4.49×10^{15}



INSTRUCTIONS FOR USE:

1. By weight, thoroughly mix 100 parts 20-3305 Resin to 25 parts 20-3305 Catalyst.
2. For optimal results, cure for four hours at 120°C. Alternatively, cure for 16 hours at 85°C

IMPORTANT:

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